GLOBALFOUNDRIES 130, 90, 55, 45, 40, 28, 22nm PROTOTYPING AND VOLUME PRODUCTION

Through EUROPRACTICE-IC, customers from both academic and private sectors can access Multi-Project-Wafer and Volume Production services of GLOBALFOUNDRIES.

Why EUROPRACTICE?

► Affordable and easy access to Prototyping and Small Volume Production services for academia and industry.

► MPW (Multi-Project-Wafer) runs for various technologies, including ASICs, Photonics, MEMS and GaN.

► Advanced packaging, system integration solutions and test services.

Why GLOBALFOUNDRIES?

► The world's leading specialty foundry with the flexibility to meet the dynamic needs of clients.

► Broad range of platforms and features, such as RF CMOS, FDSOI, RFSOI, SiGe, FinFET, SiPh.

► Technology nodes ranging from 350nm down to 12nm.

► 22nm and 28nm nodes fabricated in Dresden, Germany.

Technology Highlights

GF 130LP and 130BCDlite

The highly configurable and production-proven 130nm platform solution enables integration of logic, RF, analog and non-volatile memory to provide a cost effective solution. 130LP technology is ideal for volume production serving Mobile Cellular, Consumer and Digital/RF SoC. 130BCDLite process is tailored for cost-effective mobile/consumer applications such as DC-DC, AC-DC, PMIC, Wireless and Quick Charging.

GF SiGe 8HP

GF's SiGe 8HP technology drawn at 130nm features low noise figures, high linearity, gain, breakdown and operating voltages, together with simplified impedance matching and excellent thermal stability. Advanced SiGe heterojunction bipolar transistors (HBTs) provide superior low-current and high-frequency performance while enabling the technology to operate at high junction temperatures.

GF SiPh 90WG

This 90nm silicon photonics technology features best-in-class performance in key parameters, including SOI waveguide loss, undercut thermal phase shifter, input/output single mode fiber fiber-to-chip coupling loss and optical return loss. Moreover, it has Mach-Zehnder Interferometer (MZI) and photodiode bandwidth.

GF 55LPe-RF and 55LPx

Built on the company's low power enhanced (LPe) platform, 55nm RFCMOS technology combines the benefits of a rich baseline logic technology and IP ecosystem with RF features and PDKs, enabling a seamless transition to digital logic SoCs with higher levels of RF integration. The 55nm Low Power Extended (LPx) platform is ideal for mixed-signal / RF applications with flexible mixed-technology options for RF, eFlash, high voltage and automotive.

GF 45RFSOI

45RFSOI takes advantage of a 45nm partially-depleted SOI server-class technology base that has been extensively evaluated for use in mmWave applications and in high volume production at multiple GF fabs since 2008. Today, this baseline process has RF-centric enablement, topped with device and technology additions, including thick copper and dielectric back-end-of-line (BEOL) features which enable 45RFSOI to handle the demanding performance requirements of 5G solutions.

GF 40LP-RF-mmWave

The GF 40LP process is aimed for power- and price-sensitive applications, such as mobile and wireless. In addtition, it has flexible mixed-technology options for RF, low voltage and automotive solutions. Using a multi-Vt baseline logic process, the 40nm LP-RF technology adds RF-specific features and provides mmWave coverage for active and passive elements.

GF 28SLP-RF

The 28nm Super Low Power (SLP) utilizes High-k Metal Gate (HKMG) "Gate First" technology and offers complete RF modelling for high performance RF-SoC applications. As a result, it provides superior Performance, Power, Area and Cost (PPAC) characteristics, optimized scalability (die size, design compatibility, performance) and manufacturability.

GF 22FDX

GF 22FDX employs 22nm Fully-Depleted Silicon-On-Insulator (FD-SOI) technology that delivers outstanding performance at extremely low power with the ability to operate at 0.4V ultra-low power and at 1pA per micron for ultra-low standby leakage. It has Integrated RF and mmWave devices for 5G architectural innovation and reduced system cost.

Technology Details

130LP	130BCDlite	8HP
Core Voltage: 1V/1.2V/1.5V	Core Voltage: 1.5V/5V/30V	Core Voltage: 1.2V/2.5V
I/O Voltage: 1.8V/2.5V/3.3V	I/O Voltage: 1.5V/5V/30V	Metal layers: 5 - 8
Metal layers: 2 - 8	Metal layers: 4 - 8	HBT ft/fmax (GHz): 200/265
2 core device Vt's	2 core device Vt's	High Breakdown: 3.5V Bvceo @ 60GHz ft
High endurance EEPROM Module	Iso- and low Rds(on) N/PLDMOS (10V-40V)	µ/mmWave passive elements
MIM capacitor, eFuse fuse/macro	HRES, Zener diode, MIM, MOM capacitors, eFlash	Inductors and Tx lines

90WG	55LPe-RF and 55LPx	45RFSOI
Core Voltage: 1.2V	Core Voltage: 1.2V/2.5V	Core Voltage: 0.9V/1V
Metal layers: 6	I/O Voltage: 1.8V/2.5V/3.3V	Metal layers: 7 – 8
Single wire and coupled wire CPW, eFuse, VNCAP, Inductors	Metal layers: 6 – 8	3 core device Vt's (HVt, SVt, UVt)
O-band (1310 nm) direct detect transceivers, intra-data center, NRZ, PAM4, 4xcWDM	3µm thick top metal	High ft/fmax (290/410 GHz)
	3 core device Vt's (HVt, RVt, LVt)	FET stacking for higher PA Pout and PAE
	APMOM, MIM and MOS Caps	High and low density MIM Caps
	5V EDMOS, MOS Varactor, eFuse	

40LP-RF-mmWave	28SLP-RF	22FDX
Core Voltage: 1.1V	Core Voltage: 1V	Core Voltage: 0.4V - 0.8V
I/O Voltage: 1.5V/1.8V/2.5V/3.3V	I/O Voltage: 1.5V/1.8V	I/O Voltage: 1.2V/1.5V/1.8V/3.3V
Metal layers: 6 – 8	Metal layers: 6 – 11	Metal layers: 7 – 10
4 core device Vt's	4 core device Vt's	4 core device Vt's
3µm thick top metal	3µm thick top metal	34x Ultra Thick Top metal
High ft: 260 GHz	High ft: 310 GHz	Reference flow for back-gate biasing
Large suite of Millimeter wave passive structures	Value-added RF devices for RFSOC integration	Integrated RF/mmWave devices with high ft/fmax